PCN Number:		20	20130327000				PCN Da	ite:	03	/28/2013	
Title: Additional Pb Free Lead Finish and expansion of capacity (ASE-Shanghai) for Selected SOIC (D) products.											
Customer Contact: PCN_ww_ac		vw_admir	Imin_team@list.ti.com Phone: +1(214)48)48	0-6037	Dep	t:	Quality Services	
Proposed 1 st Ship Dat		p Date:	te: 06/28/2013		Estimated Sample Availability:				As stated below		
Change	Type:										
Assembly Site		;		Assembly Process			Assembly	y Mate	eria	ls	
Design				Electrical Specification			Mechanical Specification				
Test	Site			Packing/Shipping/Labeling			Test Process				
Waf	er Bump S	Site		Wafer Bump Material			Wafer Bump Process				
	er Fab Site			Wafer Fab Ma				Wafer Fab Process			
					N Detail	s					
Descrip	tion of Cl	nange:									
 Texas Instruments is pleased to announce flexibility of supply with the qualification of Matte Sn finish as an additional Lead Free (Pb Free) Leadframe finish and expansion of capacity by qualifying ASE-Shanghai (China) facility for selected SOIC devices. ASE-Shanghai is a qualified Assembly and Test site for Texas Instruments (PCN# 20100218001) Upon expiry of this PCN TI will combine lead free solutions in a single <u>standard part number</u>, for example; <u>ULN2003ADR</u> – can ship with both Matte Sn and NiPdAu/Ag. Example: Customer order for 7500units of ULN2003APWR with 2500 units SPQ (Standard Pack Quantity per Reel). TI can satisfy the above order in one of the following ways. 3 Reels of NiPdAu finish. 2 Reels of Matte Sn and 1 reel of NiPdAu finish. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. Note: TI part numbers with "G4" or "G3" suffix are <u>NOT</u> affected by this PCN, for example 											
ULN2003ADRG4 or ULN2003ADRG3. Reason for Change:											
Continuity of supply. Improve customer service with supply flexibility and improved lead times.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
TI does not anticipate any negative impact from this change.											

Changes to product identification resulting from this PCN:

TI will maintain traceability and identification per JEDEC guidelines.

There is **No Change** in product identification and packing labels. TI will continue to follow the J-STD-609 industry standard to identify Pb Free Leadframe Finish options on packaging label and package symbolization.

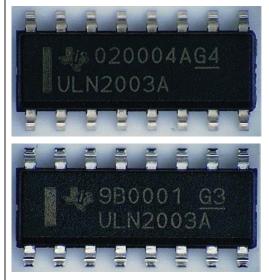
Customers will be able to clearly identify Leadframe finish from the ECAT code on package symbolization and labels.

Package symbolization:

No Change to package level symbolization. Symbolization contains the recommended ECAT symbol in addition to TI Lot Trace Code and device name.

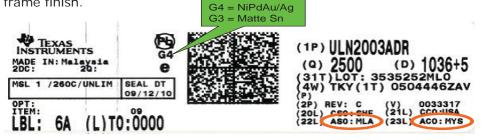
G4 = Green products with NiPdAu/Ag Lead Finish

G3 = Green products with Matte Sn lead finish.

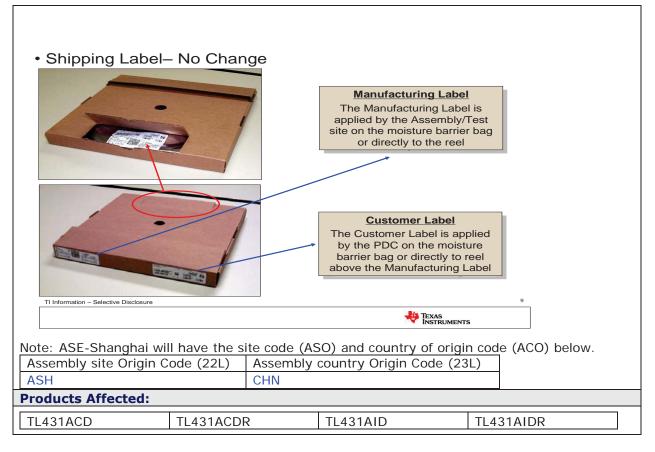


Packing/shipping Label

No change to TI Manufacturing Label and Customer Label (if applicable). Each reel, pizza boxes and standard packing boxes includes the correct ECAT symbols based on the appropriate lead frame finish.



Each "pizza box" and reel will carry the appropriate label clearly identfying lead finish as described above.



Qualification Data				
Qual Vehicle 1: ULN2003AD				
Construction Details				
Assembly Site:	ASE Shanghai	Mold Compound:	SID#EN2000509	
# Pins-Designator, Family:	16-D, SOIC	Mount Compound:	SID#EY1000063	
Leadframe (Finish, Base):	Sn	Bond Wire:	0.8 Mil Dia. Au	
Fab Process	JI Bipolar	Wafer Fab	SHE	

Qualification: 🗌 Plan	🛛 Test Results				
		Conditions			
Reliability Test	Conditions				
*Steady State Life Test	300 Hrs	300 Hrs			
*Thermal Shock	1000 cycles		77/0, 77/0, 77/0		
*Biased Hast	96 Hrs		77/0, 77/0, 77/0		
*High Temp Storage Bake	150C, 1000 Hrs		77/0, 77/0, 77/0		
*Temperature Cycle	-65C/150C, 1000 cy	ycles	77/0, 77/0, 77/0 77/0, 77/0, 77/0		
*Autoclave	96 Hrs				
Salt Atmosphere	-	-			
Flammability	(UL-1694)		5/0, 5/0, 5/0 5/0, 5/0, 5/0		
Flammability	(UL-94V-0)				
Flammability	(IEC 695-2-2)		5/0, 5/0, 5/0		
Moisture Sensitivity	MSL 1 / 260C		12/0, 12/0, 12/0		
Physical Dimensions	Per mechanical drav	Per mechanical drawing			
Bond Strength	76 Ball Bonds	76 Ball Bonds			
Die Shear	-		15/0, 15/0, 15/0		
Lead Fatigue	-		22/0, 22/0, 22/0		
Lead Pull	-	-			
Lead Finish Adhesion	-	-			
Solderability	8 Hrs/Steam Age	22/0, 22/0, 22/0			
X-Ray	Top Side Only	5/0, 5/0, 5/0			
Visual mechanical	Approved by AT Site	Pass			
Electrical Test Manufacturability-TQ	Approved by AT Site	Approved by AT Site & Product Engineer			
	Qual Vehicle	Qual Vehicle 2: HC04DR			
	Constructio	n Details			
Assembly Site:	ASE-Shanghai	E-Shanghai Mold Compound:			
# Pins-Designator, Family:	14-D, SOIC	Mount Compound:	SID#EY1000063		
Leadframe (Finish, Base):	Sn	Sn Bond Wire:			
Fab Process	HCMOS	ICMOS Wafer Fab			
Qualification: 🗌 Plan	Test Results	☐ Test Results			
		Sample Size			
Reliability Test	Conditions	Conditions			
*High Temp Storage Bake	150C, 1000 Hrs				
*Temperature Cycle	-65C/150C, 1000 cy	77/0, 77/0, 77/0			
Bond Strength	76 Ball Bonds	76 Ball Bonds			
Die Shear	-	-			
Visual mechanical	Approved by AT Site	Pass			
X-Ray	Top Side Only	5/0, 5/0, 5/0			
Assembly Manufacturability	Approved by AT Site	Pass			
Electrical Test	Approved by AT Site	Approved by AT Site & Product Engineer			
Manufacturability-TQ		Approved by AT Site & Froduct Engineer			

Qual Vehicle 3: LM358AD					
Construction Details					
Assembly Site:	ASE-Shanghai Mold Compound:		SID#EN2000509		
# Pins-Designator, Family:	-D, SOIC Mount Compound:		SID#EY1000063		
Leadframe (Finish, Base):	Sn Bond Wire:		Au		
Fab Process	JI Bipolar	Wafer Fab	SHE		
Qualification: 🗌 Plan 🛛 Test Results					
Reliability Test	Conditions	Sample Size (PASS/FAIL) 3 Lots			
Bond Strength	76 Ball Bonds	76/0, 76/0, 76/0			
Die Shear	-	15/0, 15/0, 15/0			
Visual mechanical	Approved by AT Sit	Pass			
X-Ray	Top Side Only	5/0, 5/0, 5/0			
Assembly Manufacturability	Approved by AT Sit	Approved by AT Site			
Electrical Test Manufacturability-TQ	Approved by AT Sit	Pass			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com